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April 14, 2003

To: Examiner Michael Luhrs
USPTO
Art Unit 2824
FAX: 703-746-7473

From: George SimionYour Ref.: 09/843,924Our Ref.: 109182Number of Pages Sent (Including cover sheet): 6Prepared By: gps**Comments:**

Examiner Luhrs,

I have enclosed a copy of the Supplemental Amendment filed in the USPTO on April 11.

Please call if you have any questions regarding the Supplemental Amendment.

Thank you.

George Simion

Sent by: GPS

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PATENT APPLICATION**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re the Application of

Kazunori SAKURAI et al.

Group Art Unit: 2824

Application No.: 09/843,924

Examiner: Michael K. Lubrs

Filed: April 30, 2001

Docket No.: 109182

For: METHOD FOR FORMING BUMP, SEMICONDUCTOR DEVICE AND METHOD
FOR MAKING THE SAME, CIRCUIT BOARD, AND ELECTRONIC DEVICE

SUPPLEMENTAL AMENDMENT

Director of the U.S. Patent and Trademark Office
Washington, D.C. 20231

Sir:

As supplement to the Amendment filed February 20, 2003, please further amend the
above-identified application as follows:

IN THE CLAIMS:

Please replace claim 1:

1. (Amended) A method for forming a bump, comprising:
forming a resist layer that defines a through hole which overlaps at least a
portion of a pad;
forming an opening in an insulating film after forming the resist layer, the
opening exposing at least a part of the pad;
forming a metal layer after forming the opening, the metal layer connected to
the portion of the pad exposed at the opening; and
forming a bump connected to the pad after forming the metal layer.